



# SOT786-3

plastic thermal enhanced small outline package; 8 leads;  
body width 3.9 mm; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSO8
<b>Package type industry code</b>	HSO8
<b>Package style descriptive code</b>	HSO (thermal enhanced small outline)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-2-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.8	-	4.9	5	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	1.43	-	1.55	1.68	mm
A <sub>2</sub>	package height	1.43	-	1.5	1.58	mm
e	nominal pitch	-	-	1.27	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	

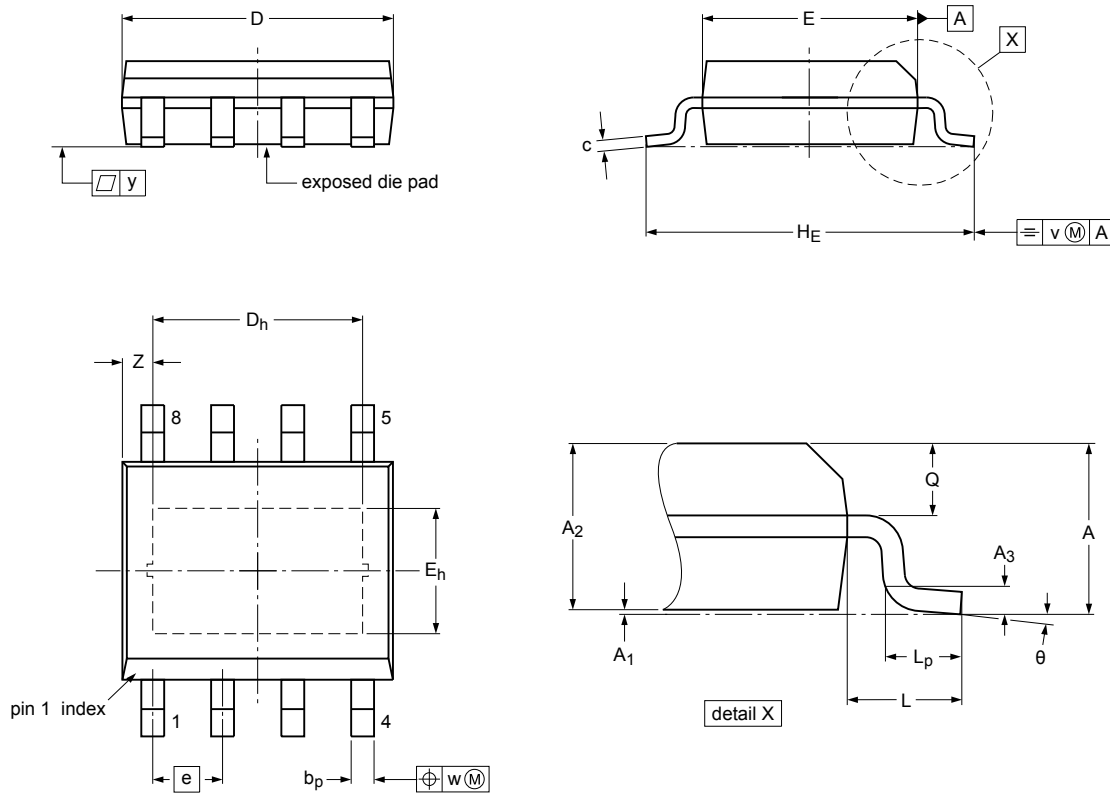


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## 2. Package outline

HSO8: plastic thermal enhanced small outline package;  
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Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z	θ
max	1.68	0.10	1.58		0.49	0.25	5.00	3.91	4.00	2.39		6.20		0.89	0.75				0.7	8°
nom	1.55	0.05	1.50	0.25	0.41	0.20	4.90	3.81	3.90	2.29	1.27	5.99	1.05	0.64	0.65	0.25	0.25	0.1	0.5	5°
min	1.43	0.00	1.43		0.35	0.19	4.80	2.95	3.80	2.19		5.84		0.41	0.55				0.3	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot786-3\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT786-3					-13-06-05- 15-02-12

Fig. 1. Package outline HSO8 (SOT786-3)

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### 3. Legal information

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Date of release: 8 February 2016

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